



Realize Your Product Promise®

# 2019 R3

C A P A B I L I T I E S

# CONTENT

## STRUCTURES

Geometric Idealization.....	3
Modeling Capabilities .....	4
Materials.....	4
Composite Materials .....	5
Structural Solver Capabilities.....	5
Topology Optimization .....	6
Multi Analysis .....	7
Vibrations .....	7
Nonlinear Transient Dynamics.....	8
Explicit Dynamics.....	8
Durability.....	9
Wave Hydrodynamics.....	9
Thermal.....	10
Additional Physics.....	10
Optimization .....	11
Miscellaneous and Usability.....	11
HPC - Structures .....	12

## FLUIDS

General Solver Capabilities .....	13
Single Phase Non-Reacting Flows.....	14
Heat Transfer.....	14
Particles Flows (Multiphase).....	15
Free Surface Flows (Multiphase) .....	15
Dispersed Multiphase Flows (Multiphase).....	16
Reacting Flows .....	17
Turbomachinery .....	18
In-Flight Icing .....	18
Optimization .....	19
High Rheology Material.....	20
HPC - Fluids.....	20
Pre and Post Processing.....	21
Multiphysics.....	21

Fluid-Structure Interacton.....	21
Electro-Thermal Interaction.....	21
Other Coupled Interactions .....	22
Ease of Use and Productivity.....	22

## ELECTRONICS

Low Frequency Electromagnetics .....	23
Magnetic Transient.....	23
Advanced Magnetic Modeling.....	23
High Frequency Electromagnetics .....	24
Power and Signal Integrity Board Simulation Capabilities .....	27
RLCG Parasitic Extraction.....	28
Electronics Cooling.....	29
HPC for Electronics.....	30

## SYSTEMS MODELING - ELECTRONIC PRODUCTS

System Modeling for Power Electronics.....	31
System Modeling for RF/Microwave...	31
System Modeling for SI/PI.....	32

## MULTIPHYSICS

Platform Technologies.....	32
Electro-Thermal Interaction.....	33
Miscellaneous .....	33

## SYSTEMS & EMBEDDED SOFTWARE

System Simulation, Validation and Digital Twins.....	34
Functional Safety Analysis.....	34
Model-based Systems Engineering....	35

Embedded Control Software Development.....	35
Man-Machine Interface Software.....	36
AV Perception Software Testing.....	37

## VRXPERIENCE

Human Vision.....	37
Headlamp Simulation.....	37
Optical System Simulation .....	37
Context Simulation.....	38
Rendering Engine.....	38
VR .....	38
Solver.....	38
Acoustics & Sound Quality .....	39

## GEOMETRY .....

## DESIGN TOOLS

Structural.....	41
Fluid.....	41
Thermal.....	42
Electromagnetics.....	42
Multiphysics.....	42
Design & Concept Modeling.....	43
Manufacturing.....	43
3D Printing.....	43
Reverse Engineering .....	43
Interfaces and Add-Ons.....	43

## ADDITIVE SOLUTIONS

Additive Prep.....	44
Topology and Lattice Optimization .	44
Geometry and STL File Handling .....	45
Workbench Additive .....	45

Additive Print .....	46
Additive Science .....	47

## OPTICAL

General Solver Capabilities .....	48
Photometry.....	48
Human Vision.....	49
Wavelength Range.....	49
Optical Design .....	49
Optical Sensors.....	50
Head-Up Display .....	50
HPC - SPEOS .....	50
Simulation Preparation .....	50
Post Processing.....	51
Optimization.....	52

## MATERIALS

Materials Data Management .....	53
Materials Data Analysis.....	54
Workflow Management .....	54
Integration with CAD, CAE, PLM.....	54
Restricted Substances .....	55
Materials Selection & Related Tools .....	55
Data Library ANSYS Advanced Materials Data Bundles .....	56
Data Library Stalalone Data Modules.....	57
Services.....	58
Teaching Resources.....	58



STRUCTURES	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM
<b>GEOMETRIC IDEALIZATION</b>						
Spring	●	●	▲	●	●	●
Mass	●	●	●	●	●	●
Damper	●	●		●	●	
Spar	●	●	●			
Beam	●	●	●	●	●	●
Pipe/Elbow	●	●	●			
Shell - Thin	●	●	●	●	●	●
Layered Shell - Thin (Composite)	●	●		●	●	
Shell - Thick (Solid Shell)	●	●	●			
Layered Shell - Thick (Solid Shell) (Composite)	●	●	●			
2D Plane / Axisymmetric	●	●	●	●	●	
3D Solids	●	●	●	●	●	●
Layered 3D Solids (Composite)	●	●				
Infinite Domain	●	●	●	●	●	
2.5D	●	●				
Reinforced	●	●		●	●	
Coupled Field ROM Element Technology	●					
Substructuring / Matrix	●					

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 2 = ANSYS Fluent  
 3 = ANSYS DesignXplorer  
 4 = ANSYS SpaceClaim  
 5 = ANSYS Customization Suite (ACS)  
 6 = ANSYS HPC, ANSYS HPC Pack or ANSYS HPC Workgroup  
 7 = ANSYS GRANTA Materials Data for Simulation  
 8 = ANSYS Additive Suite  
 9 = ANSYS Composite Cure Simulation

DMP = Distributed-memory parallel  
 SMP = Shared-memory parallel  
 MAPDL = Mechanical APDL  
 Explicit = Autodyn  
 RBD = Rigid Body Dynamics  
 Aqwa = Aqwa

STRUCTURES	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM
<b>MODELING CAPABILITIES</b>						
Contact - Linear	●	●	●	●	●	●
Contact - Nonlinear	●	●	●	●	●	●
Joints	●	●	●	●	●	●
Spot Welds	●	●	●	●	●	
Element Birth and Death	●	●				
Gasket Elements	●					
Rezoning and Adaptive Remeshing	●			●	●	
Inverse Analysis	●					
<b>MATERIALS</b>						
Basic Linear Materials (Linear, Anisotropic, Temperature Dependent)	●	●	●	●	●	●
Basic Nonlinear Materials (Hyper, Plasticity, Rate Independent, Isotropic, Concrete)	●	●	▲	●	●	▲
Advanced Nonlinear Materials (Rate dependent, Anisotropic, Damage Models, Geomechanics Materials, Multiphysics)	●			●	●	
Field Dependent	●	●		●		
Reactive Materials	●					
Fracture Mechanics and Crack Growth	●					
Material Designer	●					
GRANTA Materials Data for Simulation	■ <sup>7</sup>	■ <sup>7</sup>	■ <sup>7</sup>			

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STRUCTURES	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM
<b>COMPOSITE MATERIALS</b>						
Material Definitions	●	●		●	●	
Layers Definitions	●	▲		●	●	
Interface Plies	●					
Advanced Modeling Features	●					
Variable Material Data	●					
Solid Extrusion	●					
Lay-Up Mapping	●					
Draping	●					
Lay-Up Exchange Interfaces	●					
Advanced Failure Criteria Library	●					
First-Ply Failure	●	●				
Last-Ply failure	●					
Delamination	●			●	●	
Composite Cure Simulation	■ <sup>9</sup>					
<b>STRUCTURAL SOLVER CAPABILITIES</b>						
Linear Static	●	●	●			●
Nonlinear Static	●	●	●			●
Pre-Stress Effects, Linear Perturbation	●	●	●	▲	▲	
Nonlinear Geometry	●	●	●	●	●	●

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<b>STRUCTURAL SOLVER CAPABILITIES (CONTINUED)</b>						
Buckling - Linear Eigenvalue	●	●	●			●
Buckling - Nonlinear Post Buckling Behavior	●	●	●		●	●
Buckling - Nonlinear Post Buckling Behavior - Arc Length	●	●				
Steady State Analysis Applied to a Transient Condition	●					
Advanced Wave Loading	●					
<b>TOPOLOGY OPTIMIZATION</b>						
Structural Optimization	●	●	●			●
Modal Optimization	●	●	●			●
Thermal Loads	●	●	●			
Inertial Loads	●	●	●			
Optimized Design Validation	●	●	●			●
Manufacturing Constraints	●	●	●			▲
Stress constraints	●	●	●			●
Symmetry	●	●	●			●
Lattice Optimization	■ <sup>8</sup>					
Overhang/Additive Constraints	■ <sup>8</sup>					

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<b>MULTI ANALYSIS</b>						
Submodeling	●	●	●			
Data Mapping	●	●	●			●
Multiphysics Data Mapping	●	●				
Initial State	●	●		●	●	
Advanced Multi-Stage 2-D to 3-D Analysis	●	●				
<b>VIBRATIONS</b>						
Modal	●	●	●			●
Modal - Pre-Stressed	●	●	●			●
Modal - Damped/ Unsymmetric	●	●				
Transient - Mode-Superposition	●	●				
Harmonic - Mode-Superposition	●	●				
Harmonic - Full	●	●				
Spectrum	●	●				
Random Vibration	●	●				●
Mistuning	●	●				
Rotordynamics	●	●				
Modal Acoustic	●					
Harmonic Acoustic	●					

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<b>NONLINEAR TRANSIENT DYNAMICS</b>						
Rigid Body Mechanisms	●	●				
Rigid Body Dynamics with CMS L Components for Flexible Bodies	●					
Full Transient	●	●		●	●	
CMS with Substructuring	●					
<b>EXPLICIT DYNAMICS</b>						
FE (Lagrange) Solver	●			●	●	
Euler Solvers				●		
Meshless Solvers	●			●		
Implicit-Explicit Deformations	●			●	●	
Implicit-Explicit Material States	●			●		
Fluid-Structure Interaction (FSI)	●			●		
Mass Scaling	●			●	●	
Natural Fragmentation	●			●		
Erosion Based on Multiple Criteria	●			●	●	
De-Zoning				●	●	
Part Activation and Deactivation (Multi Stage Analysis)				●		
Remapping in Space				●		
Remapping Solution Methods				●		

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STRUCTURES	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM
<b>DURABILITY</b>						
Stress-Life (SN)	●	●	●			●
Strain-Life (EN)	●	●	●			●
Dang Van	■ <sup>1</sup>	■ <sup>1</sup>	■ <sup>1</sup>			
Safety Factor	●	●	●			●
Adhesive Bond	■ <sup>1</sup>	■ <sup>1</sup>	■ <sup>1</sup>			
Crack Growth Linear Fracture Mechanics	■ <sup>1</sup>	■ <sup>1</sup>	■ <sup>1</sup>			
Seam Weld	■ <sup>1</sup>	■ <sup>1</sup>	■ <sup>1</sup>			
Spot Weld	■ <sup>1</sup>	■ <sup>1</sup>	■ <sup>1</sup>			
Thermo-Mechanical Fatigue	■ <sup>1</sup>	■ <sup>1</sup>	■ <sup>1</sup>			
Vibration Fatigue	■ <sup>1</sup>	■ <sup>1</sup>	■ <sup>1</sup>			
Virtual Strain Gauge Correlation	■ <sup>1</sup>	■ <sup>1</sup>	■ <sup>1</sup>			
Python Scripting Customization	■ <sup>1</sup>	■ <sup>1</sup>	■ <sup>1</sup>			
<b>WAVE HYDRODYNAMICS</b>						
Diffraction and Radiation	●					
Frequency & Time Domain Motions Analysis	●					
Moorings, Joints & Tethers	●					
Load Transfer to Structural Analysis	●					

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<b>THERMAL</b>						
Steady State Thermal	●	●	●			●
Transient Thermal	●	●	●			●
Conduction	●	●	●	●	●	●
Convection	●	●	●			●
Radiation to Space	●	●	●			●
Radiation - Surface to Surface	●	●	●			
Phase Change	●	●	●	●	●	
Thermal Analysis of Layered Shells and Solids	●	●	●			
<b>ADDITIONAL PHYSICS</b>						
1-D Thermal-Flow	●	●	●			
1-D Coupled-Field Circuits	●					
1-D Electromechanical Transducer	●					
MEMS ROM	●					
Piezoelectric	●					
Piezoresistive	●					
Electroelastic	●					
Electromagnetic	●					▲
Vibro-Acoustics	●					
Electro-Migration	●					

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<b>ADDITIONAL PHYSICS (CONTINUED)</b>						
Diffusion-Pore-Fluid	●					
Diffusion-Thermal Structural-Electric	●					
Structural-Thermal-Electric-Magnetic	●					▲
1-Way Fluid-Structure Interaction	■ <sup>2</sup>	■ <sup>2</sup>	■ <sup>2</sup>			●
2-Way Fluid-Structure Interaction	■ <sup>2</sup>					
<b>OPTIMIZATION</b>						
DesignXplorer Included	●	●	●	■ <sup>3</sup>	■ <sup>3</sup>	●
Parameters	●	●	●	●	●	●
Design Point Studies	●	●	●	●	●	●
Correlation Analysis	●	●	●	●		●
Design of Experiments	●	●	●	●		●
Sensitivity Analysis	●	●	●	●		●
Goal Driven Optimization	●	●	●	●		●
Six Sigma Analysis	●	●	●	●		●
<b>MISCELLANEOUS AND USABILITY</b>						
ANSYS SpaceClaim	●	■ <sup>4</sup>	■ <sup>4</sup>	■ <sup>4</sup>	■ <sup>4</sup>	●
ANSYS Customization Suite (ACS)	●	■ <sup>5</sup>	■ <sup>5</sup>	■ <sup>5</sup>	■ <sup>5</sup>	●
Support ACT Extensions	●	●	●	●	●	●
Command Snippet Support	●	●	●			●

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STRUCTURES	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM
<b>MISCELLANEOUS AND USABILITY (CONTINUED)</b>						
Batch run capability	●	●	●	●	●	
Read/Write 3rd Party Matrix CAE Data	●	●		●	●	
CDB and 3rd party FE Model Import	●	●	●		●	
Nastran Bulk File Export	●	●	●			
<b>HPC - STRUCTURES</b>						
Default Number of Cores	4 (DMP + SMP) MAPDL 4 for Explicit 4 for RBD MAPDL 4 for AQWA	4 (DMP + SMP)	4 (DMP + SMP)	1	1	4 (DMP + SMP) MAPDL
Parallel Solving on Local PC	●	●	●	●	●	●
Parallel Solving on Cluster	●	●	●	●	●	
GPU Acceleration	MAPDL - ■ <sup>6</sup> Explicit - No RBD - No AQWA - No	■ <sup>6</sup>	■ <sup>6</sup>			
Parallel Solving with ANSYS Cloud Launched from Desktop	MAPDL - Yes Explicit - No RBD - No AQWA - No	MAPDL - Yes RBD - No	MAPDL - Yes			

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FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>GENERAL SOLVER CAPABILITIES</b>							
Comprehensive Inlet and Outlet Conditions	●	●	●	●	●	●	●
Steady-State Flow	●	●	●	●	●	●	●
Transient Flow	●	●	●	●	●	●	●
2-D and 3-D Flow	●	▲	●	▲	●	▲	▲
Reduced Order Models (ROM)	●						●
Time Dependent Boundary Conditions	●	●	●	●	●	▲	●
Customizable Materials Library	●	●	●	●	●	●	●
Fan Model	●	●			●		
Periodic Domains	●	●	●	●	●	●	●
Flow-Driven Solid Motion (6DOF)	●	●			●		
Pressure-Based Coupled Solver	●	●	●	●	●	●	●
Density-Based Coupled Solver	●	●					●
Dynamic/Moving-Deforming Mesh	●	●	●	●	●		●
Overset Mesh	●						
Immersed-Solid/MST Method for Moving Parts		●	●		●		
Automatic On-the-Fly Mesh Generation with Dynamic Refinement	●			●			●
Dynamic Solution-Adaptive Mesh Refinement	●	●		●	▲		●
Polyhedral Unstructured Solution-Adaptive Mesh Refinement	●						

FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>SINGLE PHASE, NON-REACTING FLOWS</b>							
Incompressible Flow	●	●	●			●	●
Compressible Flow	●	●		●	●	●	●
Porous Media	●	●	●			▲	
Non-Newtonian Viscosity	●	●	●			●	
Turbulence - Isotropic	●	●	●	●	●	●	●
Turbulence - Anisotropic (RSM)	●	●					
Turbulence - Unsteady (LES/SAS/DES)	●	●					●
Turbulence - Laminar/Turbulent Transition	●	●			●	●	●
Flow Pathlines (Massless)	●	●	●			●	
Acoustics (Source Export)	●	●			●		
Acoustics (Noise Prediction)	●	▲					
<b>HEAT TRANSFER</b>							
Natural Convection	●	●			●	●	●
Conduction & Conjugate Heat Transfer	●	●			●	●	●
Shell Conduction (Including Multi-Layer Model)	●						
Internal Radiation - Participating Media	●	●	●		●		●
Internal Radiation - Transparent Media	●	●					●
External Radiation	●	●				●	●

FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>HEAT TRANSFER (CONTINUED)</b>							
Solar Radiation & Load	●	●					
Simplified Heat Exchanger Model	●						
Non-Equilibrium Thermal Model	●						
Prorous Media	●						
<b>PARTICLES FLOWS (MULTIPHASE)</b>							
Coupled Discrete Phase Modeling including Thin Wall Films	●	●		●	●	▲	●
Macroscopic Particle Model	●					▲	
Inert Particle Tracking (With Mass)	●	●				▲	
Liquid Droplet (Incl. Evaporation)	●	●		●	●		●
Combusting Particles	●	●		●	●		●
Multicomponent Droplets	●	●		●	●		●
Discrete Element Model (DEM)	●	●					
Break-Up And Coalescence	●	●		●	●		●
Erosion	●	●					
<b>FREE SURFACE FLOWS (MULTIPHASE)</b>							
Implicit VOF	●	●	●				
Explicit VOF	●	●	●				
Coupled Level Set/VOF	●	●			●		
VOF to DPM Spray Model	●						

FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>FREE SURFACE FLOWS (MULTIPHASE) (CONTINUED)</b>							
Open Channel Flow and Wave	●	●					
Surface Tension	●	●		●	●		
Phase Change	●	●		●	●		
Cavitation	●	●		●	●		
Cavitation Where Multiple Fluids and Non-Condensing Gases are Present	●						
<b>DISPERSED MULTIPHASE FLOWS (MULTIPHASE)</b>							
Mixture Fraction	●	●					
Eulerian Model including Thin Wall Films	●	●		●	●		
Boiling Model	●	●		●			●
Surface Tension	●	●		●			●
Phase Change	●	●		●	●		●
Drag And Lift	●	●		●	●		●
Wall Lubrication	●	●		●			●
Heat And Mass Transfer	●	●		●	●		●
Population Balance	●	●		●			●
Reactions Between Phases	●	●		●			●
Granular Model for Dense Bed of Solids	●	●					
Dense Particulate Coupling (DDPM)	●	●					



FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>REACTING FLOWS</b>							
Species Transport	●	●	●	●			●
Non-Premixed Combustion	●	●		●			●
Premixed Combustion	●	●		●			●
Partially Premixed Combustion	●	●		●			●
Composition PDF Transport	●	●					
Finite Rate Chemistry	●	●	●	●			●
Pollutants and Soot Modeling	●	●		●			●
Sparse Chemistry Solver with Dynamic Cell Clustering and Dynamic Adaptive Chemistry	●			●			●
Ability to Use Model Fuel Library Mechanisms	●			●			●
Flame-speed from Fuel-Component Library	●			●			●
DPIK Spark-Ignition Model				●			●
Flame-Propagation Using Level-Set Method (G-Equation)				●			●
Internal Combustion Engine Specific Solution	●			●			●
0-D/1-D/2-D Reactor Models and Reactor Networks							●
Plasma Reactions							●
Comprehensive Surface-Kinetics	●						●
Chemical and Phase Equilibrium	●						●
Flamelet table generation	●						●

FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>REACTING FLOWS (CONTINUED)</b>							
Flamespeed and Ignition Table Generation							●
Reaction Sensitivity, Uncertainty and Path Analysis							●
Surrogate Blend Optimizer							●
Mechanism Reduction							●
<b>TURBOMACHINERY</b>							
MRF/Frozen-Rotor	●	●					
Sliding-Mesh/Stage	●	●					
Transient Blade Row		●					
Pitch Change		●					
Time Transformation		●					
Fourier Transformation		●					
Harmonic Analysis		●					
Blade Flutter Analysis		●					
Forced Response Analysis		●					
Flank Milled Blades		●					
<b>IN-FLIGHT ICING</b>							
Simulation of Standard Droplets, SLD, and Ice Crystals	●				●		
Inclusion of Vapor / Humidity Effects on Icing	●				●		

FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>IN-FLIGHT ICING (CONTINUED)</b>							
Icing Environments of Appendices C, O (SLD), and D (Ice Crystals)	●				●		
Various Pre-Defined Droplet Size Distributions	●				●		
Simulation of Rime, Glaze, and Mixed Icing	●				●		
Single-and Multi-Shot Icing Simulations with Mesh Deformation for Prediction of Ice Accretion and Aerodynamic Performance Degradation	●				●		
Single-and Multi-Shot Icing Simulations with Automatic Re-Meshing for Prediction of Ice Accretion and Aerodynamic Performance Degradation					●		
Conjugate Heat Transfer (CHT) for Anti-and De-Icing Simulations					●		
Icing of Rotating Components of All Types: Rotors, Propellers, and Engines (Fan, Guide Vanes, and Any Number of Compressor Rows)					▲		
<b>OPTIMIZATION</b>							
Parameters	●	●	●			●	●
Design Point Studies	●	●	●			●	●
Correlation Analysis	●	●	●			●	
Design of Experiments	●	●	●			●	
Sensitivity Analysis	●	●	●			●	●
Goal Driven Optimization	●	●	●			●	

FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>OPTIMIZATION (CONTINUED)</b>							
Six Sigma Analysis	●	●	●			●	
Adjoint Solver for Shape Optimization	●						
Adjoint Solver Supports Rotating Reference Frames & Conjugate Heat Transfer	●						
Multi-Objective-Constrained Optimization	●						
Mesh Morphing (RBF Morph)	■						
<b>HIGH RHEOLOGY MATERIAL</b>							
Viscoelasticity			●				
Specialty Extrusion Models			●			▲	
Specialty Blow Molding Models			●			▲	
Specialty Fiber Spinning Models	●						
<b>HPC - FLUIDS</b>							
Parallel Solving On Local PC Option	●	●	●	●	●	●	●
Parallel Solving Over Network Option	●	●	●	●	●	●	
Parallel Solving Over Cloud Launched from Desktop	●						
GPU Support	●		●				
Parallel mesh generation	●						

FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>PRE AND POST PROCESSING</b>							
Photo Realistic Rendering	●	●	●	●	●	●	●
SpaceClaim Direct Modeler	●	●	●	●	●	●	●
Compare Multiple Runs, Datasets, Physics, Graphs in a Single Window	●	●	●	●	●	●	●
<b>MULTIPHYSICS</b>							
Advanced, Automated Data Exchange	●	●	●		●	●	
Accurate Data Interpolation Between Dissimilar Meshes	●	●			●	●	
Drag-n-Drop Multiphysics	●	●	●				
Direct Coupling Between Physics	●	●				●	
Collaborative Workflows	●	●				●	
Fully Managed Co-Simulation	●	●					
Flexible Solver Coupling Options	●	●			●		
<b>FLUID-STRUCTURE INTERACTION</b>							
Force Induced Motion/ Deformation	■	■	●			●	
Fluid Thermal Deformation	■	■				●	
<b>ELECTRO-THERMAL INTERACTION</b>							
Convection Cooled Electronics	●	●					
Conduction Cooled Electronics	●	●					
High Frequency Thermal Management	●	●					
Electromechanical Thermal Management	●	●					

FLUIDS	CFD ENTERPRISE						CHEMKIN ENTERPRISE
	CFD PREMIUM		POLYFLOW	FORTE	FENSAP-ICE	AIM	
	FLUENT	CFX					
<b>OTHER COUPLED INTERACTIONS</b>							
Aero-Vibro Acoustics	●						
Acoustics-Structural	●	●					
Fluid Magnetohydrodynamics	●	●					
<b>EASE OF USE AND PRODUCTIVITY</b>							
Support ACT Simulation Apps	●						
Mosaic-Enabled Meshing Technology	●						
Task-Based Workflow - Watertight Geometries	●						
Task-Based Workflow - Fault Tolerant Geometries	●						
Directly Enter Expressions	●	●				●	
Parallel Solving with ANSYS Cloud Launched from Desktop	●						

<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>					
<b>LOW FREQUENCY ELECTROMAGNETICS</b>											
Electrostatics	●					●					
AC Conduction	●					●					
DC Conduction	●					●					
Magnetostatics	●					●					
Adaptive Field Mesh	●	●	●	●		●					
AC Harmonic Magnetic	●					●					
Electric Transient	●										
<b>MAGNETIC TRANSIENT</b>											
Translational Motion	●										
Fully Automatic Symmetrical Mesh Generation	●										
Rotational Motion	●										
Non-Cylindrical Motion	●										
Advanced Embedded Circuit Coupling	●										
Circuit Coupling with Adaptive Time Stepping	●										
Direct and Iterative Matrix Solvers	●										
<b>ADVANCED MAGNETIC MODELING</b>											
Vector Hysteresis Modeling	●										
Hysteresis Modeling for Anisotropic Material	●										
Frequency Dependent Reduced Order Models	●										

<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>ADVANCED MAGNETIC MODELING (CONTINUED)</b>										
Equivalent Model Extraction (Linear-Motion, Rotational-Motion, No-Motion)	●									
Functional Magnetization Direction	●									
Magnetization/De-Magnetization Modeling	●									
Manufacturing Dependent Core L Loss Models	●									
Noise – Vibration Modeling	■									
Temperature De-Magnetization Modeling	●									
Core Loss Computation	●									
Lamination Modeling	●									
Magnetostriction and Magnetoelastic Modeling	●									
Hardware in the Loop modeling	●									
Integrated Motor Synthesis and Design Kit	●									
Integrated Planar Magnetics Synthesis and Design Kit	●									
Litz Wire Modeling	●									
<b>HIGH FREQUENCY ELECTROMAGNETICS</b>										
Fully Automated Adaptive Mesh Refinement		●								
Multi-Frequency Broadband Adaptive Meshing		●								
Frequency Domain Finite Element (FEM) Analysis		●								
Frequency Domain Integral Equation (MoM) Analysis		●								



<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>HIGH FREQUENCY ELECTROMAGNETICS (CONTINUED)</b>										
Time Domain FEM Analysis		●								
FEM Eigenmode Analysis		●								
MoM Characteristic Mode Analysis		●								
Physical Optics (PO) Analysis		■								
Shooting and Bouncing Ray+ (SBR+) Analysis		■								
Physical Theory of Diffraction (PTD) Correction for SBR		■								
Uniform Theory of Diffraction (UTD) Correction for SBR		■								
Visual Ray Tracing for SBR+ Analysis		■								
SBR+ Creeping Wave Correction for RCS of Curved Objects		■								
Range Doppler Plots for Radar Scenario Analyses		■								
Accelerated Doppler Processing (ADP) for SBR+ Range Doppler Analyses		■								
Domain Decomposition Method (DDM) for Frequency Domain FEM Analysis		●								
Hybrid Finite Element/ Integral Equation Analysis		●								
UI Coupled Finite Element and/or IE with SBR+ Analysis		●								
Modal Wave Port Excitation		●								
Terminal Wave Port Excitations		●								
Lumped, Voltage and Current Excitations		●								

● Full Support    ▲ Limited Capability    ■ Requires more than 1 product

<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>HIGH FREQUENCY ELECTROMAGNETICS (CONTINUED)</b>										
Circuit Port Excitations		●								
Parametric Antenna Excitations for SBR+		●								
Floquet Excitations		●								
Incident Wave Excitation		●								
Magnetic Ferrite Bias Excitation		●								
Perfect Electric and Magnetic Boundary		●								
Finite Conductivity Boundary		●								
Lumped RLC Boundary		●								
Symmetry Boundary		●								
Periodic Boundary		●								
Frequency Dependant Materials		●								
Spatial XYZ Material Properties Via Dataset		●								
Higher and Mixed Order Elements		●								
Curvilinear Element Mesh Correction		●								
S,Y,Z Matrix Results		●								
E, H, J, P Field Results		●								
Direct and Iterative Matrix Solvers		●								
Antenna Parameter Calculation		●								
Infinite and Finite Antenna Array Calculations		●								
Radar Cross Section Calculation		●								

● Full Support    ▲ Limited Capability    ■ Requires more than 1 product

<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>HIGH FREQUENCY ELECTROMAGNETICS (CONTINUED)</b>										
FSS, EBG and Metamaterial Calculation		●								
Specific Absorption Rate Calculation		●								
EMI/EMC Calculation		●								
System Level EMI and RFI Analysis		●								
Linear Circuit Analysis with EM Dynamic link		●								
Integrated Antenna Synthesis and Design Kit		●								
Radar Prep/Post Simulation Wizards		●								
3D Component Libraries with User Controlled Parametrics		●								
3D Component with Encryption Creation		●								
3D Component with Encryption Utilization		●								
Multipaction Solver		●								
<b>POWER AND SIGNAL INTEGRITY BOARD SIMULATION CAPABILITIES</b>										
Electronics Desktop 3D Layout GUI		●	●		●					
ECAD Translation (Altium, Cadence, Mentor, Pulsonix, & Zuken)		●	●							
MCAD (.sat) Generation from ECAD		●	●							
Lead Frame Editor		●	●							
DC Voltage, Current and Power Analysis for PKG/PCB			●							
DC Joule Heating with ANSYS Icepak			●	●	●					

<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>POWER AND SIGNAL INTEGRITY BOARD SIMULATION CAPABILITIES (CONTINUED)</b>										
Passive Excitation Plane Resonance Analysis			●							
Driven Excitation Plane Resonance Analysis			●							
Automated Decoupling Analysis			●							
Capacitor Loop Inductance Analysis			●							
AC SYZ Analysis - PI, SI, & EMI			●							
Dynamically Linked Electromagnetic Field Solvers			●							
Chip, Package, PCB Analysis (CPM)		●	●							
Near-Field EMI Analysis			●							
Far-Field EMI Analysis			●							
Characteristic Impedance (Zo) L PKG/PCB Scan			●							
Full PCB/PKG Cross-talk Scanning			●							
TDR Analysis		●	●	●						
Transient IBIS Circuit Analysis		●	●							
SerDes IBIS-AMI Circuit Analysis			●							
Macro-Modeling (Network Data Explorer)			●							
Steady State AC (LNA) Analysis			●							
Virtual Compliance - DDRx, GDDRx, & LPDDRx			●							
Synopsys HSPICE Integration			●							

<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>POWER AND SIGNAL INTEGRITY BOARD SIMULATION CAPABILITIES (CONTINUED)</b>										
Cadence PSPICE Support			●							
Electromagnetically Circuit Driven Field Solvers		●	●							
<b>RLCG PARASITIC EXTRACTION</b>										
DCRL, ACRL & CG Solver				●						
IC Packaging RLCG IBIS Extraction for Signals & Power				●						
Touchpanel RLCG Unit Cell Extraction				●						
Adaptive Meshing for Accurate Extraction				●						
Bus Bar RLCG Extraction				●						
Power Inverter & Converter Component Extraction				●						
Specialized Thin Plane Solver for Touchpanel Extraction				●						
3D Component Library		●		●						
Reduced RLCG Matrix Operations				●						
SPICE Equivalent Modeling Export				●						
DCRL & ACRL Joule Heating Analysis with Icepak				●						
Macro-Modeling (Network Data Explorer)				●	●					
2D Transmission Line Modeling Toolkit				●						
2D Cable Modeling Toolkit				●						

<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>ELECTRONICS COOLING</b>										
Multi-Mode Heat Transfer					●	●				
Steady-State and Transient					●	●				
CFD Analysis					●	●				
Turbulent Heat Transfer					●	●				
Multiple-Fluid Analysis					●					
Species Transport					●					
Solar Loading					●					
Reduced Order Flow and Thermal					●					
Network Modeling					●					
Joule Heating Analysis	■	■	■	■	●	●				
Thermo-Electric Cooler Modeling					●	●				
Thermostat Modeling					●					
Package Characterization					●					
Data Center Modeling					●					
<b>HPC FOR ELECTRONICS</b>										
GPU Support	■	■								
HPC Accelerated Frequency Sweeps		●	●							
HPC Distributed Hybrid Solving		●								
HPC Enabled Domain Decomposition Method	●	●								
HPC Time Decomposition Method	●									
HPC Enabled Multi-port Excitation Acceleration		●								
HPC Acceleration for DCRL, ACRL and CG				●						
HPC Enabled Parallel Processing	●	●		●	●					

<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>SYSTEMS MODELING - ELECTRONICS PRODUCTS</b>										
<b>SYSTEM MODELING FOR POWER ELECTRONICS</b>										
Circuit Simulation	●	●	●	●	●	●				
Block Diagram Simulation	●	●	●	●	●	●				
State Machine Simulation	●	●	●	●	●	●				
VHDL-AMS Simulation	●	●	●	●	●	●				
Integrated Graphical Modeling Environment	●	●	●	●	●	●				
Power Electronics Component Libraries	●	●	●	●	●	●				
Reduced Order Modeling	●	●	●	●	●	●				
Power Electronic Device and Module Characterization	●	●	●	●	●	●				
Co-Simulation with MathWorks Simulink	●	●	●	●	●	●				
<b>SYSTEM MODELING FOR RF/MICROWAVE</b>										
Radio Frequency Interference (RFI) System Solver		■								
Electromagnetic Interference System Solver		■								
RF Link Budget Analysis		■								
RF Co-Site and Antenna Coexistence Analysis		■								
Automated Diagnostics for Rapid Root-Cause Analysis		■								
RF Component Library		■								
Wireless Propagation Models		■								
Multi-Fidelity Parametric Radio Models		■								
Antenna-to-Antenna Coupling Models		■								

<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>SYSTEMS MODELING - ELECTRONICS PRODUCTS (CONTINUED)</b>										
<b>SYSTEM MODELING FOR SI/PI</b>										
SerDes channel modeling - IBIS-AMI, QuickEye and VerifEye		■	●							
Multi-drop & parallel bus modeling - IBIS, HSPICE, Spectre, PSPICE, and Nexxim Transient		■	●							
Network Data Exploration		●	●	●						
TDR analysis		■	●							
Steady State AC (LNA) Analysis		■	●							
Virtual Compliance - DDRx, GDDRx, & LPDDRx		■	●							
<b>MULTIPHYSICS</b>										
<b>PLATFORM TECHNOLOGIES</b>										
Advanced, Automated Data Exchange	●	●		●	●					
Accurate Data Interpolation Between Dissimilar Meshes	●	●		●	●					
Drag-n-Drop Multiphysics	●	●		●	●					
Direct Coupling Between Physics	●	●		●	●					
Collaborative Workflows	●	●		●	●					
Fully Managed Co-Simulation	●	●		●	●					
Flexible Solver Coupling Options	●	●		●	●					



<b>ELECTRONICS</b>	<b>MAXWELL</b>	<b>HFSS</b>	<b>SIWAVE</b>	<b>Q3D EXTRACTOR</b>	<b>ICEPAK</b>	<b>AIM</b>				
<b>MULTIPHYSICS (CONTINUED)</b>										
<b>ELECTRO-THERMAL INTERACTION</b>										
Convection Cooled Electronics		●			●					
Conduction Cooled Electronics		●			●					
High Frequency Thermal Management		●		●	●					
Electromechanical Thermal Management	●			●	●					
<b>MISCELLANEOUS</b>										
Integrated Windows HPC Support	●	●	●	●	●					
Integrated IBM Spectrum LSF Support	●	●	●	●	●					
Customizable 3rd Party Scheduler Support	●	●	●	●	●					
Support ACT Extensions	▲	▲	▲	▲	▲	▲				
Parallel Solving with ANSYS Cloud Launched from Desktop	●	●	●	●						

<b>SYSTEMS &amp; EMBEDDED SOFTWARE</b>	<b>TWIN BUILDER</b>	<b>MEDINI ANALYZE</b>	<b>SCADE ARCHITECT</b>	<b>SCADE SUITE</b>	<b>SCADE DISPLAY</b>	<b>SCADE VISION</b>	<b>VRXPERIENCE FOR AV/ADAS</b>	<b>VRXPERIENCE HMI</b>	<b>VRXPERIENCE PERCEIVED QUALITY</b>	<b>VRXPERIENCE SOUND</b>
<b>SYSTEM SIMULATION, VALIDATION AND DIGITAL TWINS</b>										
Integrated Graphical Modeling Environment	●									
Standard Modeling Languages and Exchange Formats	●									
Multi-domain Systems Modeler	●									
Extensive OD Application-Specific Libraries	●									
3rd Party (1D) Tool Integrations	●									
3D ROM	●									
Embedded Software Integration	●									
Multi-Domain System Simulation	●									
Rapid HMI Prototyping	●									
System Optimization	●									
XIL Integration	●									
IIoT Connectivity	●									
Digital Twin Runtime Deployment	●									
<b>FUNCTIONAL SAFETY ANALYSIS</b>										
Safety Concept Modelling		●								
Model Based Safety Analysis		●								
Reliability Prediction and Analysis		●								
Traceability and Validation Teamwork		●								
Integration into Engineering Environment		●								

SYSTEMS & EMBEDDED SOFTWARE	TWIN BUILDER	MEDINI ANALYZE	SCADE ARCHITECT	SCADE SUITE	SCADE DISPLAY	SCADE VISION	VRXPERIENCE FOR AV/ADAS	VRXPERIENCE HMI	VRXPERIENCE PERCEIVED QUALITY	VRXPERIENCE SOUND
<b>FUNCTIONAL SAFETY ANALYSIS (CONTINUED)</b>										
Customization and Process Adaption		●								
ANSYS Product Integration		●								
Reporting and Documentation		●								
<b>MODEL-BASED SYSTEMS ENGINEERING</b>										
Model-Based System Design			▲	▲						
Functional Decomposition			▲	▲						
Architecture Decomposition			●	●						
Allocation Of Functions To Components			●	●						
Model Checks			●	●						
Model Diff/Merge			●	●						
System / Software Bi-Directional Sync			●	●						
Model Sharing And IP Protection			●	●						
Model-Based Interface Control Document Production			●	●						
Configurable For Industry Standards (IMA, AUTOSAR, Etc.)			●	●						
Product Configuration for Automotive Developers			●	●						
<b>EMBEDDED CONTROL SOFTWARE</b>										
Data Flow and State Machine Design and Simulation Capabilities				●						
Extensive Set of Libraries Delivered as Design Examples				●						

<b>SYSTEMS &amp; EMBEDDED SOFTWARE</b>	<b>TWIN BUILDER</b>	<b>MEDINI ANALYZE</b>	<b>SCADE ARCHITECT</b>	<b>SCADE SUITE</b>	<b>SCADE DISPLAY</b>	<b>SCADE VISION</b>	<b>VRXPERIENCE FOR AV/ADAS</b>	<b>VRXPERIENCE HMI</b>	<b>VRXPERIENCE PERCEIVED QUALITY</b>	<b>VRXPERIENCE SOUND</b>
<b>EMBEDDED CONTROL SOFTWARE (CONTINUED)</b>										
Simulation Capabilities				●						
Record and Playback Scenarios				●						
Plant Model Co-Simulation Including FMI				●						
Coverage Analysis for Requirements Based Tests				●						
Formal Verification				●						
Timing and Stack Optimization				●						
Worst Case Execution Time Estimates on Target				●						
Verification of Stack Space Requirements				●						
Certified Code Generation for DO-178C, EN 50128, ISO 26262, IEC 61508				●						
Certification Kits for DO-178C, EN50128, ISO 26262, IEC 61508				●						
<b>MAN-MADE INTERFACE SOFTWARE</b>										
Model-Based Prototyping And Specification Of MMIs					●					
Support Of OpenGL, OpenGL SC and OpenGL ES					●					
Font Management					●					
Optimization Of Graphical Specifications					●					
Plant Model Co-Simulation Including FMI					●					
Automatic Generation of iOS and Android Projects					●					
Certified Code Generation For DO-178C, EN 50128, ISO 26262, IEC 61508					●					

SYSTEMS & EMBEDDED SOFTWARE	TWIN BUILDER	MEDINI ANALYZE	SCADE ARCHITECT	SCADE SUITE	SCADE DISPLAY	SCADE VISION	VRXPERIENCE FOR AV/ADAS	VRXPERIENCE HMI	VRXPERIENCE PERCEIVED QUALITY	VRXPERIENCE SOUND
<b>MAN-MADE INTERFACE SOFTWARE (CONTINUED)</b>										
Certification Kits for DO-178C, EN50128, ISO 26262, IEC 61508					●					
Testing Capabilities					●					
<b>AV PERCEPTION SOFTWARE TESTING</b>										
AV Perception Software Robustness Testing						●				
Triggering Events Identification						●				
Automatic Safety Report Generation						●				
<b>VRXPERIENCE</b>										
<b>HUMAN VISION</b>										
Glare Simulation							●			
<b>HEADLAMP SIMULATION</b>										
Virtual Measurement							●			
Lamp Control							●	▲	▲	
IIHS Test							●			
<b>OPTICAL SYSTEM SIMULATION</b>										
Ground-Truth Sensor							●			
Camera Sensor							●	▲	▲	
LiDAR Sensor							●			
Virtual Display								●		
HUD								●	●	
Advanced Lighting Component									●	

SYSTEMS & EMBEDDED SOFTWARE	TWIN BUILDER	MEDINI ANALYZE	SCADE ARCHITECT	SCADE SUITE	SCADE DISPLAY	SCADE VISION	VRXPERIENCE FOR AV/ADAS	VRXPERIENCE HMI	VRXPERIENCE PERCEIVED QUALITY	VRXPERIENCE SOUND
<b>VRXPERIENCE (CONTINUED)</b>										
<b>CONTEXT SIMULATION</b>										
Basic Driving Scenario							●	▲	▲	
Advanced Driving Scenario							■	■		
Advanced Vehicle Dynamic							■	■		
Environement Creation							■	●	●	
Trigger & Animation								●	●	
MiL/SiL Connectivity							●	●		
HiL Connectivity							●			
Virtual Display & Actuators Interaction								●		
<b>RENDERING ENGINE</b>										
Real-Time Physics-Based Lighting							●	●	●	
Advanced Raytraced Lighting								●	●	
Full Physics GPU Lighting									●	
<b>VR</b>										
HMD								●	●	
CAVE, Powerwall								●	●	
Finger Tracking								●		
<b>SOLVER</b>										
Tolerance Variation Engine									●	

SYSTEMS & EMBEDDED SOFTWARE	TWIN BUILDER	MEDINI ANALYZE	SCADE ARCHITECT	SCADE SUITE	SCADE DISPLAY	SCADE VISION	VRXPERIENCE FOR AV/ADAS	VRXPERIENCE HMI	VRXPERIENCE PERCEIVED QUALITY	VRXPERIENCE SOUND
<i>VRXPERIENCE (CONTINUED)</i>										
<b>ACOUSTICS &amp; SOUND QUALITY</b>										
Analyze, Listen & Modify										●
Psychoacoustics, Automatic Detection and Separation, Play 3D Sound										●
Engine Sound Design										●
3D Sound for Listening Room and VR										●
Interactive Sound for Driving Simulator										●
Measure Sound Perception with Listening Test										●
Listen to ANSYS Mechanical Simulation										●

<b>GEOMETRY</b>	<b>DESIGN MODELER</b>	<b>SPACECLAIM DESIGN MODELER</b>								
Direct Modeling Technology		●								
Feature Based Modeling Technology	●									
Open Data from All Major CAD Systems	●	●								
Export Data to Neutral File Formats	●	●								
Modify Imported Geometry	●	●								
Defeaturing and Simplification Tools	●	●								
Model Repair	●	●								
Add Parameters for Design Exploration	●	●								
Extract Mid-Surfaces/Shells and Beams	●	●								
Extract Volumes & Create Inner Fluid Domains	●	●								
Extract Outer Air Enclosures	●	●								
Shared Topology for Conformal Meshing	●	●								
Booleans and Slicing	●	●								
Create Weld Bodies	●	●								
Boundary Condition Mapping	●	●								
Scripting	●	●								
Sketching and Editing Tools	●	●								
3D Comparison Tools		●								
Repair and Edit Faceted Data		●								
Icepak Integration	●	●								
Reverse Engineering Faceted Data		●								



DESIGN TOOLS	DISCOVERY ESSENTIALS	DISCOVERY STANDARD	DISCOVERY ULTIMATE						
<b>STRUCTURAL</b>									
Static Structural Analysis		●	●						
Modal Analysis		●	●						
Pre-Stressed Modal Analysis			●						
Random Vibration			●						
Linear Eigenvalue Buckling			●						
Beams, Shells, Springs, Point Masses			●						
Spatially Varying Loads			●						
Nonlinear Contact & Joints			●						
Pre-Tension Bolts & Multi-Step Analysis			●						
Basic Plasticity			●						
Large Deformation			●						
Fatigue Analysis			●						
Topology Optimization		●	●						
Linear Buckling			●						
<b>FLUID</b>									
Steady-State Flow			●						
Transient Flow		●	●						
Time-dependent Fluid Conditions		●	●						
Incompressible Flow <sup>1</sup>		●	●						
Compressible Flow <sup>1</sup>			●						
Non-Newtonian Fluids			●						
Periodic Domains			●						
Porous Media			●						
Particle Flow			●						

DESIGN TOOLS	DISCOVERY ESSENTIALS	DISCOVERY STANDARD	DISCOVERY ULTIMATE						
<b>THERMAL</b>									
Steady State Thermal		●	●						
Transient Thermal		●	●						
Time Dependent Thermal Conditions		●	●						
Conduction		●	●						
Convection		●	●						
Radiation to Space			●						
<b>ELECTROMAGNETICS</b>									
DC Conduction		●	●						
AC Conduction			●						
Electrostatics			●						
Magnetostatics			●						
AC Harmonic Magnetics			●						
<b>MULTIPHYSICS</b>									
Thermal-Stress		●	●						
Fluid-Structure Interaction			●						
Fluid-Solid Thermal (Conjugate Heat Transfer)			●						
Thermal-Electric		●	●						
Thermal-Electric-Stress		●	●						
Thermal-Electromagnetic			●						
Thermal-Electromagnetic-Stress			●						

DESIGN TOOLS	DISCOVERY ESSENTIALS	DISCOVERY STANDARD	DISCOVERY ULTIMATE						
<b>DESIGN &amp; CONCEPT MODELING</b>									
Concept Modeling or Detail Design	●	●	●						
Part/Assembly Creation or Import	●	●	●						
Large Assembly Importing	●	●	●						
2-D Drawings, BOM, Exploded Views	●	●	●						
Geometric Parameterization	●	●	●						
Sheet Metal Design	●	●	●						
<b>MANUFACTURING</b>									
Repair & Defeature Tools	●	●	●						
Sheet Metal Editing and Unfolding	●	●	●						
<b>3D PRINTING<sup>2</sup></b>									
Import, Repair, Edit Faceted Data	●	●	●						
Shelling and Infills	●	●	●						
Thickness Detection	●	●	●						
<b>REVERSE ENGINEERING</b>									
Autosurface of Scanned Data	●	●	●						
Build Solid/Surfaces on Scanned Data	●	●	●						
<b>INTERFACES AND ADD-ONS</b>									
Algoryx Momentum <sup>3</sup>	●	●	●						
Keyshot Rendering <sup>3</sup>	●	●	●						

(1) Discovery Live supports mildly compressible fluid flow up to ~Mach 0.3  
(2) Included with Discovery Standard and Ultimate  
(3) Add-on Module

ADDITIVE SOLUTIONS	ADDITIVE PREP	ADDITIVE PRINT	ADDITIVE SUITE*	MECHANICAL ENTERPRISE						
<b>ADDITIVE PREP</b>										
Define Build Envelope	●	■	●							
Multiple Parts	●	■	●							
Optimize Part Orientation based upon Distortion Tendency, Build Time, & Supports	●	■	●							
Support Regions Detection	●	●	●							
Control of Support Parameters	●	●	●							
Multiple Support Types	●	●	●							
Angled Supports	●	■	●							
Perforations, Tooth Patterns, Intrusion, Sizing and Distribution of Support Walls	●	■	●							
Automatic Support Generation	●	●	●							
Export of STL and SpaceClaim files	●	●	●							
<b>TOPOLOGY AND LATICE OPTIMIZATION</b>										
Structural Optimization				●						
Modal Optimization				●						
Thermal Loads				●						
Inertial Loads				●						
Optimized Design Validation				●						
Manufacturing Constraints				●						
Stress Constraints				●						
Symmetry				●						

ADDITIVE SOLUTIONS	ADDITIVE PREP	ADDITIVE PRINT	ADDITIVE SUITE*	MECHANICAL ENTERPRISE						
<b>TOPOLOGY AND LATTICE OPTIMIZATION (CONTINUED)</b>										
Lattice Optimization			●	■						
Overhang / Additive Constraints			●	■						
<b>GEOMETRY AND STL FILE HANDLING</b>										
SpaceClaim Direct Modeler		●	●	●						
<b>WORKBENCH ADDITIVE</b>										
Nonlinear and Temperature Dependent Material Properties			●							
Thermo-Mechanical Coupled Strain Solution			●							
Native Mechanical Environment			●							
Stress-Based Automatically Generated Supports			●							
Part Distortion & Residual Stress (As-Built)			●							
Part Distortion & Residual Stress After Support Removal			●							
Blade Crash Detection			▲							
Identification of High Strain (Crack) Locations			●							
Layer by Layer Stress & Distortion Visualizations			●							
Option to Output Only the Last Layer of the Build or Every Nth Layer			●							
User-Defined Step Option as 1st or Last Sequence Step			●							
Layered Tetrahedral Meshing			●							
Post Build Heat Treatment			●							
Import of STL Supports			●							

● Full Support    ▲ Limited Capability    ■ Requires more than 1 product

ADDITIVE SOLUTIONS	ADDITIVE PREP	ADDITIVE PRINT	ADDITIVE SUITE*	MECHANICAL ENTERPRISE						
<b>ADDITIVE PRINT</b>										
Nonlinear and Temperature Dependent Material Properties		●	●							
Uniform Assumed Isotropic Strain		●	●							
Scan Pattern Based Anisotropic Strain		●	●							
Thermal Ratcheting Based Anisotropic Strain		●	●							
Desktop & Cloud Stand-Alone Environments		●	●							
Stress-Based Automatically Generated Supports		●	●							
Part Distortion & Residual Stress (As-Built)		●	●							
Part Distortion & Residual Stress After Support Removal		●	●							
Distortion Compensation		●	●							
Blade Crash Detection		●	●							
Identification of High Strain (Crack) Locations		●	●							
Layer by Layer Stress, Distortion & Blade Crash Visualizations		●	●							
Build File Readers for Multiple AM Machines		●	●							
Auto Queue Multiple Successive Simulations		●	●							
Input Strain Hardening Factor		●	●							
Import of STL Supports		●	●							
Subvoxel Material Density Assignment		●	●							

<b>ADDITIVE SOLUTIONS</b>	<b>ADDITIVE PREP</b>	<b>ADDITIVE PRINT</b>	<b>ADDITIVE SUITE*</b>	<b>MECHANICAL ENTERPRISE</b>						
<b>ADDITIVE SCIENCE</b>										
Meltpool Dimensions			●							
Detailed Thermal History			▲							
% Porosity			●							
Sensor Measurement Predictions			▲							

\* Additive Suite requires a Mechanical Enterprise license

OPTICAL	SPEOS PRO	SPEOS PREMIUM PREP-POST PACKAGE	SPEOS ENTERPRISE	SPEOS OPTICAL PART DESIGN	SPEOS OPTICAL SENSOR TEST	SPEOS HUD DESIGN & ANALYSIS	SPEOS FAR INFRARED EXTENSION	SPEOS OPTICAL DESIGN OPTIMIZER (1)			
	PrepPOST PACKAGE			ADD-ONS							
<b>GENERAL SOLVER CAPABILITIES</b>											
Monte-Carlo Forward Ray Tracing	●	●	●								
Monte-Carlo Backward Ray Tracing		●	●								
Deterministic Simulation	▲	●	●								
Spectral Propagation	●	●	●								
Polarisation propagation	●	●	●								
Dispersion	●	●	●								
Surface Diffusion	●	●	●								
Volumic Diffusion	●	●	●								
Ambiant Material	●	●	●								
SPEOS Live Preview (GPU Acceleration)		●(2)	●(2)								
Virtual BSDF			●								
<b>PHOTOMETRY</b>											
Intensity	●	●	●								
Illuminance	●	●	●								
3D Illuminance	●	●	●								
Luminance	▲	●	●								
3D Energy Density		●	●								
360° View - Observer		●	●								
360° View - Immersive		●	●								



OPTICAL	SPEOS PRO	SPEOS PREMIUM PREP-POST PACKAGE	SPEOS ENTERPRISE	SPEOS OPTICAL PART DESIGN	SPEOS OPTICAL SENSOR TEST	SPEOS HUD DESIGN & ANALYSIS	SPEOS FAR INFRARED EXTENSION	SPEOS OPTICAL DESIGN OPTIMIZER (1)			
	PrepPOST PACKAGE			ADD-ONS							
<b>HUMAN VISION</b>											
Dynamic Adaptation			●								
Glare Simulation			●								
High Dynamic Range Screen support			●								
<b>WAVELENGTH RANGE</b>											
Visible (360nm - 830nm)	●	●	●								
UV (50nm-360 nm)		●	●								
Near IR (830nm - 2.5µm)		●	●								
Far Infra-Red (2.5µm - 100µm)							●				
<b>OPTICAL DESIGN</b>											
Parabolic Surface	●	●	●								
TIR Lens	●	●	●								
Projection Lens	●	●	●								
Optical Lens				●							
Optical Surface				●							
Light Guide				●							
Sharp Cut-Off Reflector				●							
Poly-Ellipsoidal Surface				●							
Micro Optical Stripes				● (1)							
Honeycomb Lens				●							

OPTICAL	SPEOS PRO	SPEOS PREMIUM PREP-POST PACKAGE	SPEOS ENTERPRISE	SPEOS OPTICAL PART DESIGN	SPEOS OPTICAL SENSOR TEST	SPEOS HUD DESIGN & ANALYSIS	SPEOS FAR INFRARED EXTENSION	SPEOS OPTICAL DESIGN OPTIMIZER (1)			
	PrepPOST PACKAGE			ADD-ONS							
<b>OPTICAL SENSORS</b>											
Field Of View					●						
Export Sensor Grid as Geometry					● (1)						
Camera Sensor					●						
LiDAR Sensor					●						
Camera Sensor Post Processing					●						
<b>HEAD-UP DISPLAY</b>											
HUD Optical Analysis						●					
HUD Optical Design						●					
HUD Visualisation						●					
<b>HPC- SPEOS</b>											
Default Number of Cores	(4)	(4)	(4)								
Parallel Solving on Local PC	●	●	●								
Parallel Solving on Cluster	●	●	●								
ANSYS RSM Compatibility	●	●	●								
<b>SIMULATION PREPARATION</b>											
Source Group	● (1)	● (1)	● (1)								
Geometry Group	● (1)	● (1)	● (1)								
Local Meshing	● (1)	● (1)	● (1)								
3D Textures	●	●	●								

OPTICAL	SPEOS PRO	SPEOS PREMIUM PREP-POST PACKAGE	SPEOS ENTERPRISE	SPEOS OPTICAL PART DESIGN	SPEOS OPTICAL SENSOR TEST	SPEOS HUD DESIGN & ANALYSIS	SPEOS FAR INFRARED EXTENSION	SPEOS OPTICAL DESIGN OPTIMIZER (1)			
	PrepPOST PACKAGE			ADD-ONS							
<b>SIMULATION PREPARATION (CONTINUED)</b>											
Polarisation Plate		● (1)	● (1)								
Fluorescent Converter		●	●								
Texture Mapping (Bump, Multi-Layer)		● (1)	● (1)								
Sky		●	●								
Thermic Source							●				
Earth Atmosphere Model							■				
<b>POST PROCESSING</b>											
Virtual Lighting Controller		●	●								
Photometric Numerical Certification	●	●	●								
Colorimetric Analysis	●	●	●								
Spectral Analysis		●	●								
Light Expert	●	●	●								
Layer by Source		●	●								
Layer by Face		●	●								
Layer by Sequence		●	●								
Stray Light Analysis		●	●								
Layer by Polarisation		●	●								
Visibility & Legibility			●								
Night Vision Goggle							●				
Script Automation	●	●	●								

OPTICAL	SPEOS PRO	SPEOS PREMIUM PREP-POST PACKAGE	SPEOS ENTERPRISE	SPEOS OPTICAL PART DESIGN	SPEOS OPTICAL SENSOR TEST	SPEOS HUD DESIGN & ANALYSIS	SPEOS FAR INFRARED EXTENSION	SPEOS OPTICAL DESIGN OPTIMIZER (1)			
	PrepPOST PACKAGE			ADD-ONS							
<b>OPTIMIZATION</b>											
Parameters	●	●	●								
Design of Experiment	●	●	●								
Design Optimisation								●			
ANSYS Design Xplorer(2)	●	●	●								
ANSYS optiSLang Interface(2)	■	■	■								

(1) Not available for ANSYS SPEOS

(2) Only for ANSYS SPEOS

MATERIALS	GRANTA MI	GRANTA SELECTOR	GRANTA EDUPAK	MECHANICAL & ELECTRONICS DESKTOP	ONLINE SUBSCRIPTION					
<b>MATERIALS DATA MANAGEMENT</b>										
GRANTA MI Database - 'Gold Source' System to Store Corporate Materials Information	●									
Manage Specialist Materials Data Types: Single Point, Multi-Value, Ranges, Functional, Equations	●									
Manage Meta-Data and Context for Materials: Documents, Images, Multimedia, Hyperlinks	●									
Traceability for All Materials Data	●									
Access Control	●									
Version Control	●									
Large File Storage (Via Link to Binary Large Object Stores)	●									
Multiple Unit System Support	●	●	●							
Admin UI to Setup and Configure Materials Database	●									
Template Data Structures for Key Materials Use Cases: Metals, Composites, AM, Restricted Substances	●									
Toolbox for Import, Export, Manipulation of Materials Data	●									
Web App for Fast Upload of Materials Data	●									
Browse Materials Data	●	●	●							
Edit and Update Materials Data	●	▲	▲							
Search and Query Materials Data	●	●	●							

MATERIALS	GRANTA MI	GRANTA SELECTOR	GRANTA EDUPAK	MECHANICAL & ELECTRONICS DESKTOP	ONLINE SUBSCRIPTION					
<b>MATERIALS DATA MANAGEMENT (CONTINUED)</b>										
Represent Property Data in Interactive Charts, Where Relevant	●	●	●							
Comparison Tables and Comparison Charts	●	●	●							
Generate Reports on Selected Materials Records	●									
Export Data to Excel and Third-Party Software	●	●	●							
Personalize System Homepages and User Profiles	●									
Configure Web App UI for Specific User Groups	●									
<b>MATERIALS DATA ANALYSIS</b>										
Interactive Plotting of Data: Scatter, Contour, Error Bar, Surface, Plotly, Semilogx, Semilogy, Loglog	●									
Curve Fitting	●									
Cross-Table Comparisons of Materials Data	●									
Scripting Toolkit for Python and MATLAB	●									
<b>WORKFLOW MANAGEMENT</b>										
Design and Develop Workflows	●									
Execute Workflows - Processes, Approvals, Notifications	●									
<b>INTEGRATION WITH CAD, CAE, PLM</b>										
MI:Materials Gateway Embedded App in CAE: ANSYS, Abaqus, HyperMesh, NX	●									
MI:Materials Gateway Embedded App in CAD: Creo, NX, Catia	●									

MATERIALS	GRANTA MI	GRANTA SELECTOR	GRANTA EDUPAK	MECHANICAL & ELECTRONICS DESKTOP	ONLINE SUBSCRIPTION					
<b>INTEGRATION WITH CAD, CAE, PLM (CONTINUED)</b>										
MI:Materials Gateway Embedded App in PLM: Windchill, Teamcenter	●									
MI:Enterprise Connect Data Synchronization for PLM: Teamcenter, 3DEXPERIENCE	●									
Export Data in CAE File Formats	●	●	●							
Where Used? Reporting Capability for PLM	▲									
<b>RESTRICTED SUBSTANCES</b>										
Data structures to Support Restricted Substance Analytics: Store Specs, Materials, Legislations, Substances, Parts	●									
Report on Restricted Substance Risk for Materials and Process Portfolio	●									
Build and Edit Bills of Materials within a Web App	●									
At-a-Glance Restricted Substance Compliance for a BoM	▲									
Run Reports Across Multiple BoMs	▲									
Integrate Restricted Substance Reporting with PLM, CAD	▲									
<b>MATERIALS SELECTION &amp; RELATED TOOLS</b>										
Reference Data for Materials Selection on PC/Laptop		●	●							
Interactive 'Ashby Charts' of Materials Property Space	▲	●	●							
Systematic Materials Selection Methodology		▲	●							
Filter Materials Based on Property Profile	●	●	●							

MATERIALS	GRANTA MI	GRANTA SELECTOR	GRANTA EDUPAK	MECHANICAL & ELECTRONICS DESKTOP	ONLINE SUBSCRIPTION					
<b>MATERIALS SELECTION &amp; RELATED TOOLS (CONTINUED)</b>										
Filter Materials Based on Links to Other Materials / Processes / Objects	▲	●	●							
Materials Substitution & Equivalency - 'Find Similar'		●								
Performance Index Finder		●	●							
Engineering Solver - Convert Engineering Requirements to Materials Properties		●								
Hybrid Synthesizer - Predict Properties of Hybrid Materials		●	●							
Part Cost Estimator		●	●							
Selection Reports & Export of Charts for Presentations		●	●							
Eco Audit for a Product or Conceptual Design		●	●							
Edit a CES Database (CES Constructor)		●								
<b>DATA LIBRARY - ANSYS ADVANCED MATERIALS DATA BUNDLES</b>										
MaterialUniverse - GRANTA Generic Data for Selection	●	●	●							
GRANTA Materials Data for Simulation				●						
Metals Bundle - ASM Alloy Finder	●	●								
Metals Bundle - MI-21	●	●								
Metals Bundle - StahlDat SX (European Steels)	●	●								
Metals Bundle - Steelspec (UK Steels)	●	●								
Metals Bundle - JAHM Curve Data	●	●								
Polymers Bundle - M-Base Plastics	●	●	●							



MATERIALS	GRANTA MI	GRANTA SELECTOR	GRANTA EDUPAK	MECHANICAL & ELECTRONICS DESKTOP	ONLINE SUBSCRIPTION					
<b>DATA LIBRARY - ANSYS ADVANCED MATERIALS DATA BUNDLES (CONTINUED)</b>										
Polymers Bundle - Prospector Plastics	●	●	●							
Aero Bundle - MMPDS Aero Alloys	●	●	●							
Aero Bundle - CMH-17 Composites	●	●	●							
Composites Bundle - Composites QED (AGATE & NCAMP projects)	●									
Composites Bundle - Firehole Composites	●	●								
Additive Manufacturing Bundle - Senvol Database	●	●								
<b>DATA LIBRARY - STANDALONE DATA MODULES</b>										
ASM Medical Materials Database	●				●					
ASME Boiler & Pressure Vessels Code	●	●								
Coatings Data Module	●	●								
Ecoinvent Key Materials Indicators	●	●								
ESDU MMDH Aerospace Alloys	●	●								
Global Powder Metallurgy	●	●								
Human Biological Materials	●									
NCS Colors Database	●									
NIMS Creep & Fatigue Data	●									
Product Risk Database	●									
Pantone Colors	●									
Prospector Plastics and UL Yellow Cards	●									

MATERIALS	GRANTA MI	GRANTA SELECTOR	GRANTA EDUPAK	MECHANICAL & ELECTRONICS DESKTOP	ONLINE SUBSCRIPTION				
<b>DATA LIBRARY - STANDALONE DATA MODULES (CONTINUED)</b>									
RAL Colorsets	●								
Sheet Steels	●	●							
<b>SERVICES</b>									
GRANTA MI Getting Started Services	●								
GRANTA MI Implementation Services	●								
Data Migration Services	●								
Product Training / Workshops	●	●	●						
Product Support	●	●	●						
MDMC Consortium Membership	●								
EMIT Consortium Membership	●								
AutoMatIC Consortium Membership	●								
<b>TEACHING RESOURCES</b>									
CES EduPack Level 1-3 Teaching Databases			●						
The Elements Teaching Database			●						
Materials Science & Engineering Teaching Database			●						
Sustainability Teaching Database			●						
Bioengineering Teaching Database			●						
Architecture Teaching Database			●						
Lecture Units			●						

MATERIALS	GRANTA MI	GRANTA SELECTOR	GRANTA EDUPAK	MECHANICAL & ELECTRONICS DESKTOP	ONLINE SUBSCRIPTION					
<b>TEACHING RESOURCES (CONTINUED)</b>										
Student Exercises			●							
Videos			●							
Micro-Projects			●							
White Papers			●							
Case Studies			●							
Active Learning Toolkits			●							
Data Booklets			●							
Sample Project Files			●							
Phase Diagram Tool			●							